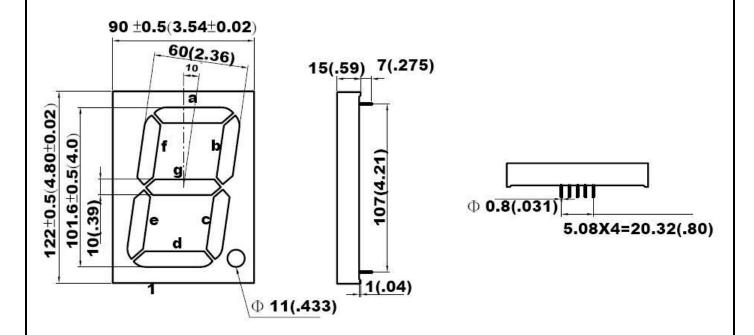
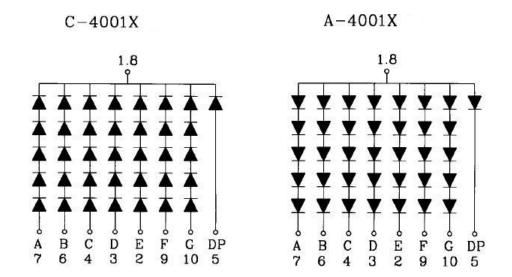


4.00" Single Digit Seven Segment Display

- 4.00 inch (101.6 mm) height
- ❖ Low power consumption
- ❖ RoHS Compliance
- Case mold type

Package Dimensions





Notes: 1. All dimensions are in millimeters (inches)

2. Tolerance is \pm 0.25mm (0.01") unless otherwise specified

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DEVICE SELECTION GUIDE

Part Number	Cl	Face / Segment	
C/A 4001E G/W	Material	Emitted Color	Gray / White
	AlGaAs	Orange-Red	Gray / White

ABSOLUTE MAXIMUM RATINGS

(Ta=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation per segment	PAD	50	mW
Peak Current per segment (1/10 Duty Cycle @1KHz)	IAF	100	mA
Continuous Forward Current per segment	IPF	30	mA
Reverse Voltage	VR	5.0	V
Operating Temperature Range	TOPR	-40~+85	°C
Storage Temperature Range	TSTG	-40~+85	°C

Solder temperature 1.6 mm from body for 3 seconds at 260°C

OPTICAL-ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Ave. Luminous Intensity	IV	IF = 10mA	18000	44000		μcd
Forward Voltage/segment	VF	IF = 10mA		9.2	12.0	V
Reverse Current/segment	IR	VR = 5V			10	uA
Spectrum Line Half-Width	Δλ	IF = 10mA		45		nm
Dominant Wavelength	λd	IF = 10mA		620		nm
Peak Wavelength	λр	IF = 10mA		630		nm



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WAVE SOLDERING

SOLDERING INSTRUCTIONS						
TYPES	DIP AND WAVE SOLDERING			IRON SOLDERING(WITH 1.5mm IRON TIP)		
	TEMPERATURE OF THE SOLDERING BATH	MAXIMUM SOLDERING TIME	DISTANCE FROM SOLDER JOINT TO CASE	TEMPERATURE OF SOLDERING IRON	MAXIMUM SOLDERING TIME	DISTANCE FROM SOLDER JOINT TO CASE
LEDS	≦260°C	38	>2mm	≦295°C	38	>2mm
	≦ 260°C	58	>4mm	≦ 295° C	58	>4mm
DISPLAYS	≦ 260°C	38	>2mm	≦ 295°C	38	>2mm



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LAMP HANDLING AND APPLICATION PRECAUTIONS

STORAGE

- 1. It is recommended to store the products in the following conditions:
 - a. Humidity: 60% RH Max
 - Temperature: $5^{\circ}\text{C} \sim 40^{\circ}\text{C} (41^{\circ}\text{F} \sim 105^{\circ}\text{F})$
 - b. Shelf life in sealed bag: 3 month < 40°C and 90% RH

FORMING

- 1. Any forming on lead pin must be done before solding, not during or after soldering
- 2. Avoid applying any stress to resin in order to prevent the epoxy fracture and break on bonding wire.
- 3. While forming, please use a tie bar cut or equivalent ot hold or bend the pin.
- 4. 2mm from the base of resin is the minimum distance for the place bending the lead pin
- 5. Avoid bending the lead pin at the same point twice or more

SOLDERING

- 1. No stress can be applied to lead pins when they are heated, otherwise disconnection may
- 2. When an LED is mounted into a P.C. board, pitch spacing should be aligned carefully to avoid causing any stress to the lead wires.
- 3. Mounting direction (electrode direction) of SMD LED and Display should be perpendicular to direction of PCB curve
- 4. After soldering, don't bend the PCB

CLEANING

- 1. Avoid using any unspecified chemical solvent to clean LED. For example, Trichoroethylene, Chlorosen, Acetone, and Diflon S3MC.
- 2. Any cleaning method can only be taken under normal temperature in one minute or less if it is required
- 3. Special attention should be taken when using any chemicals for claning because some chemicals may damage the surface of epoxy.